

Description

N-channel Enhancement Mode Power MOSFET

Features

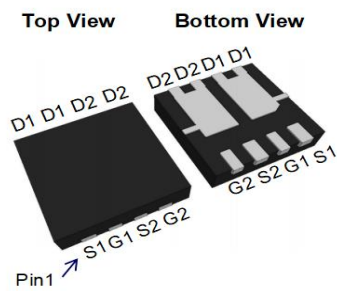
- 30V, 25A
 $R_{DS(ON)}$ Typ= 9m Ω @ $V_{GS} = 10V$
 $R_{DS(ON)}$ Typ= 13m Ω @ $V_{GS} = 4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge

Applications

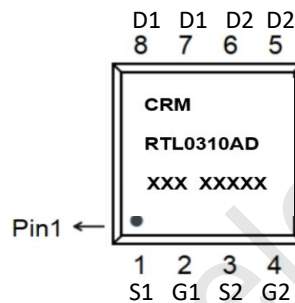
- Load Switch
- PWM Application
- Power Management



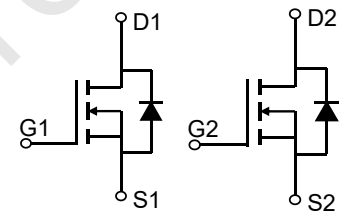
100% UIS TESTED!
100% ΔV_{ds} TESTED!



DFN3.3x3.3-8L-D



Marking and Pin Assignment



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
CRMRTL0310AD	CRMRTL0310AD	TAPING	DFN3.3x3.3-8L-D	13"	5000	50000

Absolute Maximum Ratings (@ $T_J = 25^\circ C$ unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-to-Source Voltage	30	V
V_{GS}	Gate-to-Source Voltage	± 20	V
I_D	Continuous Drain Current	$T_C = 25^\circ C$	25
		$T_C = 100^\circ C$	15
I_{DM}	Pulsed Drain Current ⁽¹⁾	100	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	36	mJ
P_D	Power Dissipation	$T_C = 25^\circ C$	34
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	59	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.7	
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150	$^\circ C$



Electrical Characteristics (T_J = 25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 30V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.5	2.2	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	V _{GS} = 10V, I _D = 15A	-	9	11	mΩ
		V _{GS} = 4.5V, I _D = 10A	-	13	16	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	-	1060	-	pF
C _{oss}	Output Capacitance		-	122	-	pF
C _{riss}	Reverse Transfer Capacitance		-	102	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 15V, I _D = 30A	-	21	-	nC
Q _{gs}	Gate Source Charge		-	3	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	5	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 15V I _D = 30A, R _{GEN} = 3Ω	-	4	-	ns
t _r	Turn-On Rise Time		-	2	-	ns
t _{d(off)}	Turn-Off DelayTime		-	13	-	ns
t _f	Turn-Off Fall Time		-	7	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	25	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	100	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 15A	-	-	1.2	V

- Notes:
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
 2. E_{AS} condition: Starting T_J=25C, V_{DD}=15V, V_G=10V, R_G=25ohm, L=0.5mH, I_{AS}=12A
 3. R_{θJA} is measured with the device mounted on a 1inch² pad of 2oz copper FR4 PCB
 4. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.

Typical Performance Characteristics

Figure 1: Output Characteristics

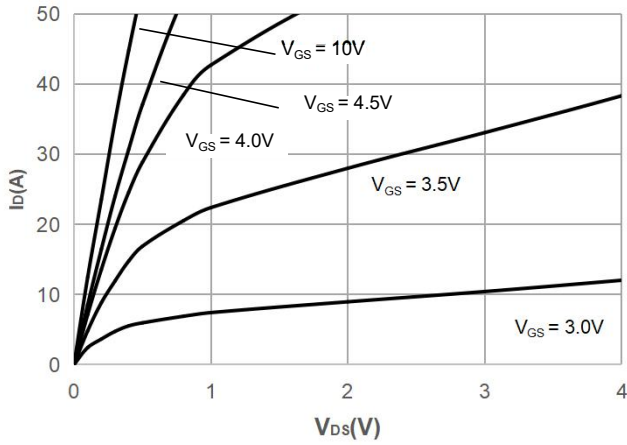


Figure 2: Typical Transfer Characteristics

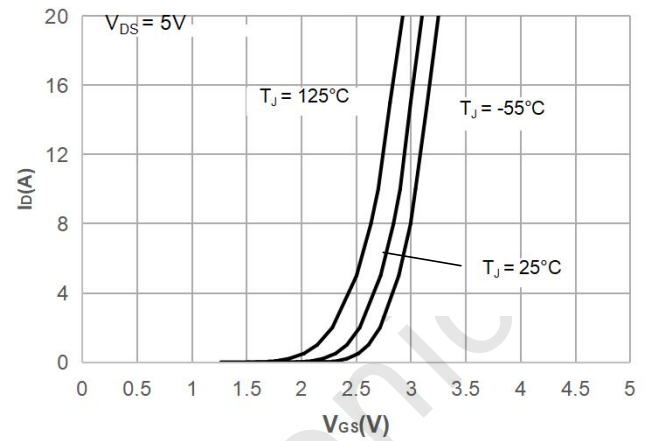


Figure 3: On-resistance vs. Drain Current

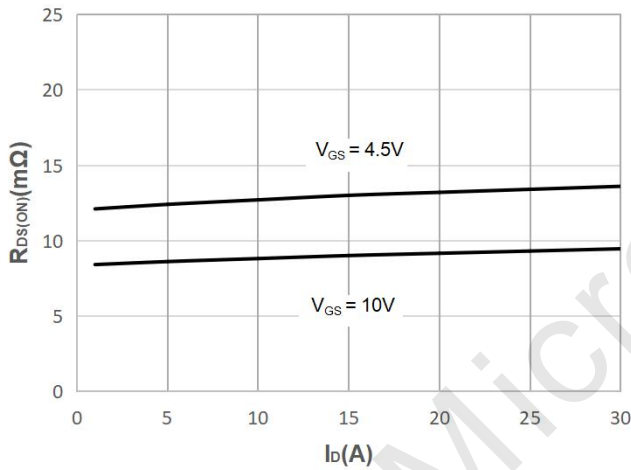


Figure 4: Body Diode Characteristics

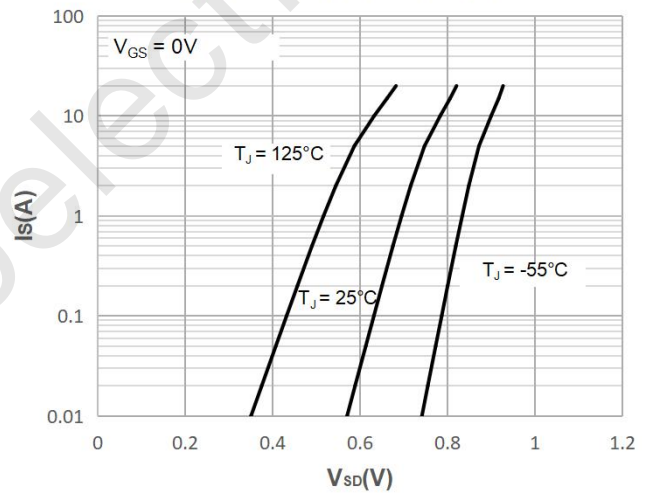


Figure 5: Gate Charge Characteristics

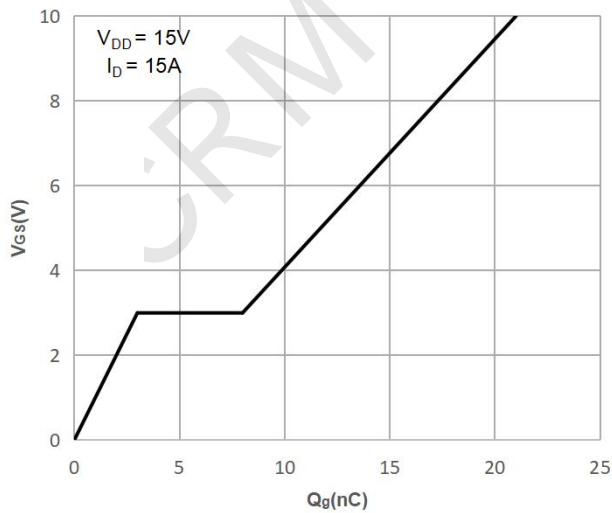
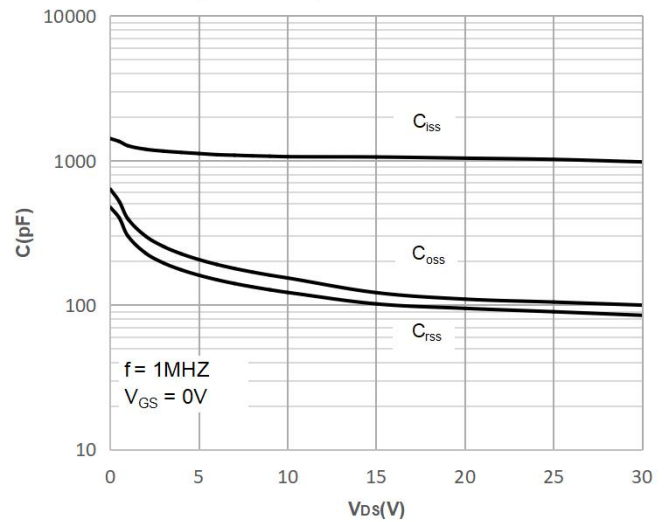


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown voltage vs. Junction Temperature

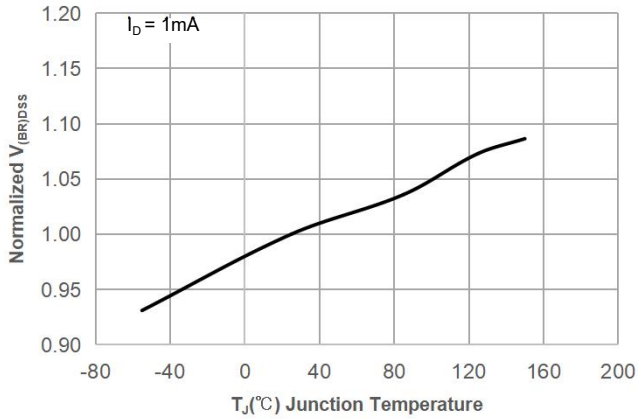


Figure 8: Normalized on Resistance vs. Junction Temperature

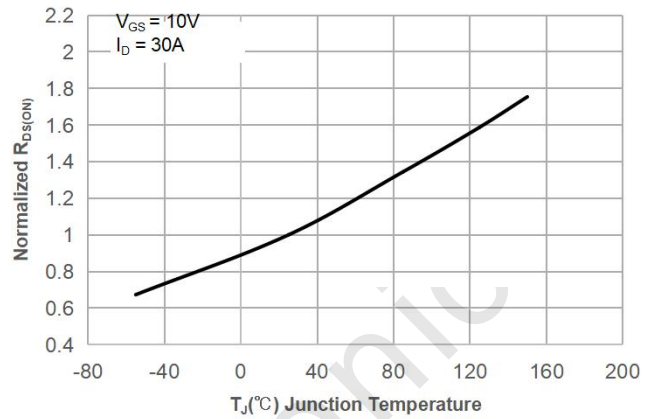


Figure 9: Maximum Safe Operating Area

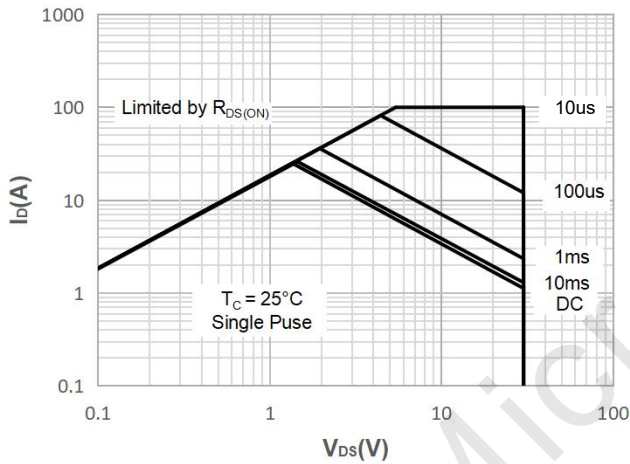


Figure 10: Maximum Continuous Drianc Current vs. Case Temperature

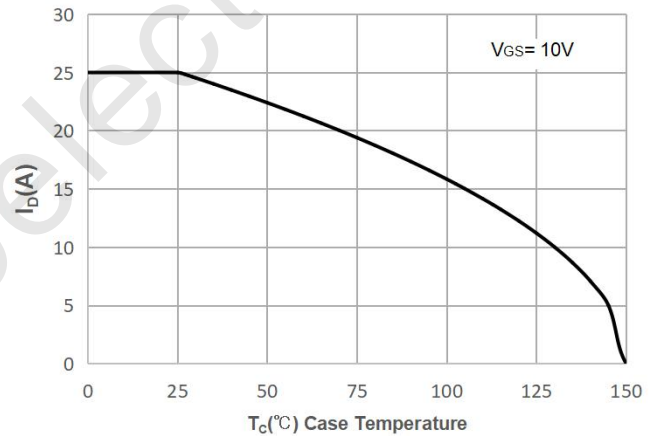


Figure 11: Normalized Maximum Transient Thermal Impedance

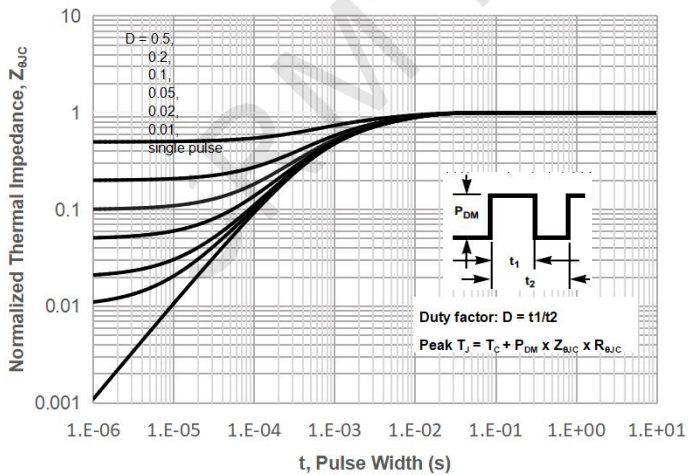
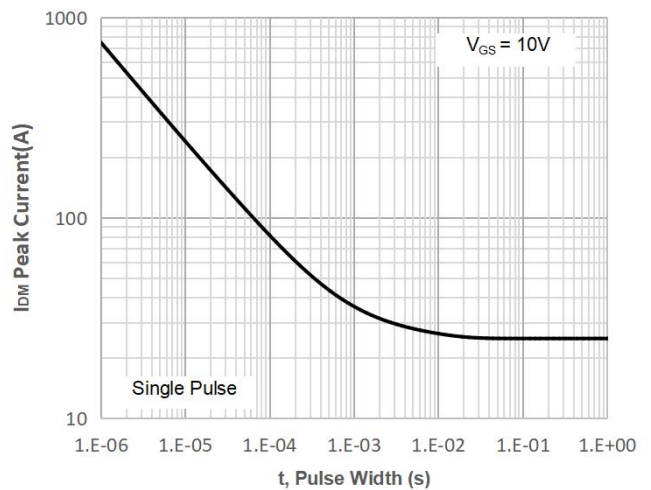


Figure 12: Peak Current Capacity



Test Circuit

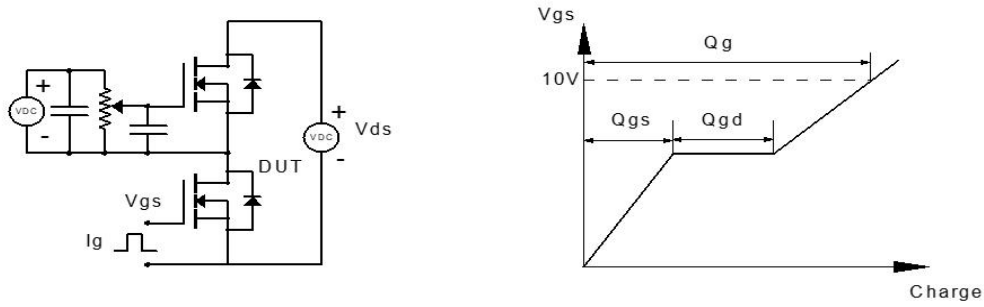


Figure 1: Gate Charge Test Circuit & Waveform

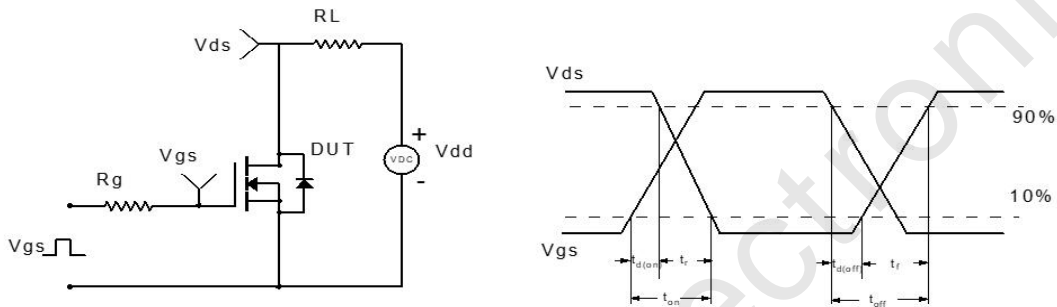


Figure 2: Resistive Switching Test Circuit & Waveform

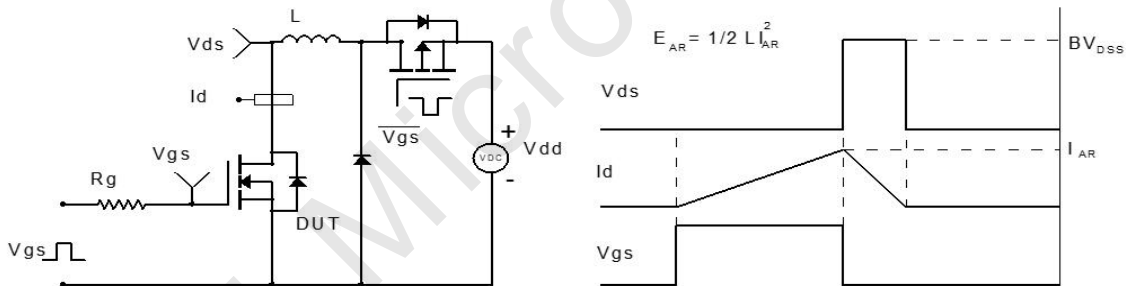


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

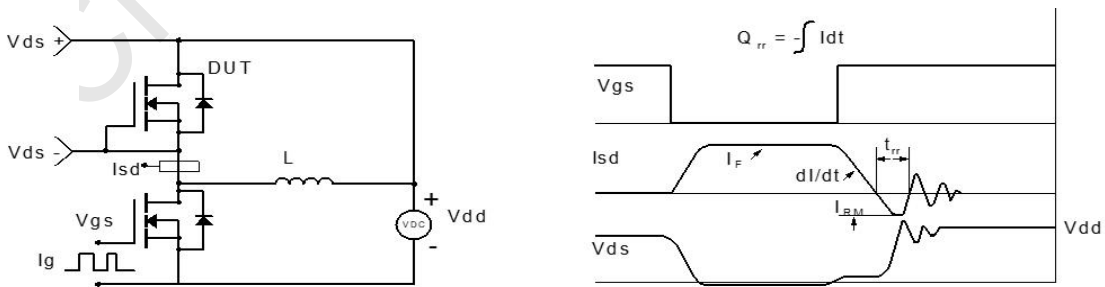
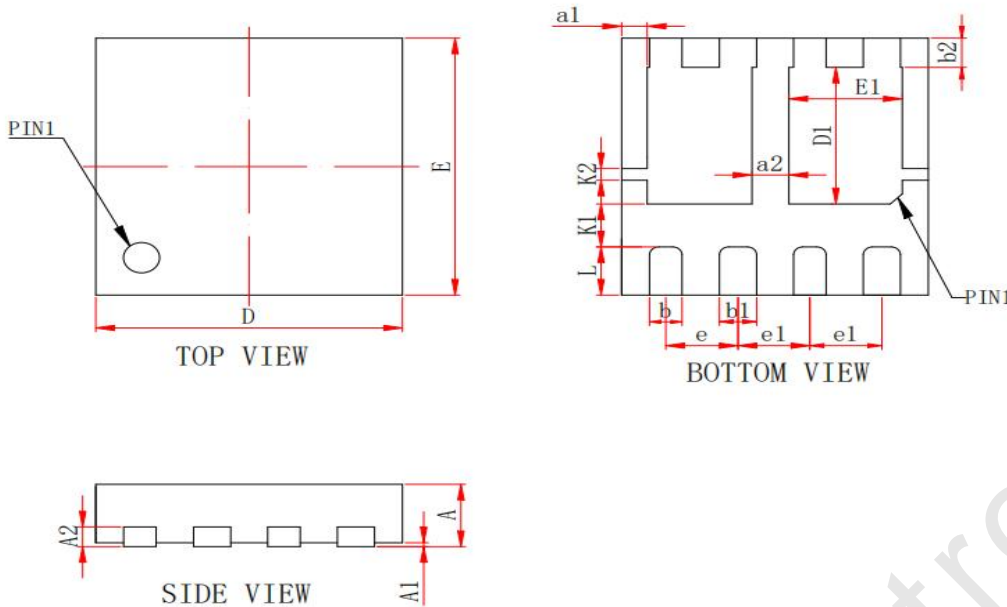


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(DFN3.3x3.3-8L-D)



STMBOL	MIN	NOM	MAX
D	3.20	3.30	3.40
E	3.20	3.30	3.40
A	0.70	0.75	0.80
A1	0.00	-	0.05
A2	0.203REF		
L	0.50	0.60	0.70
b	0.30	0.35	0.40
b1	0.35	0.40	0.45
e	0.775BSC		
e1	0.725BSC		
K1	0.500BSC		
K2	0.200BSC		
b2	0.30	0.35	0.40
E1	0.10	1.15	1.20
D1	1.70	1.75	1.80
a1	0.30	0.35	0.40
a2	0.30	0.35	0.40

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